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AmcHE
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



reapplication of:

Warren M. Farnworth
Alan G. Wood
Trung Tri Doan
David R. Hembree

RECEIVED

APR 19 1995

Art Unit: 2607

Serial No.: 08/120,628

Filing Date: September 13, 1993

Examiner: Karlsen, E.

Title: (as amended)
BONDPAD ATTACHMENTS HAVING
SELF LIMITING PROPERTIES FOR
PENETRATION OF SEMICONDUCTOR
DIE

Attorney Docket No.: 91-62.7

AMENDMENT
April 7, 1995

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Honorable Commissioner of Patents and Trademarks
Box Amendment (Non Fee)
Washington D.C. 20231

Sir:

In response to the Office Action dated January 17, 1995
having a statutory period for response set to expire on April
17, 1995, please amend the captioned case as follows:

In the claims

44. (twice amended) An attachment member for use with
a testing apparatus for testing a semiconductor integrated
circuit die, said attachment member adapted for establishing
ohmic connections with contact locations on the die,
comprising:

a) a substrate having a plurality of contacts formed
thereon;

b) the contacts projecting from a surface of the
substrate and positioned so that the contacts may be placed
in alignment with the contact locations on the die;

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4/21/95